

Packaging and Systems Facility (PASF) at Centre for Nanosciences-IISc

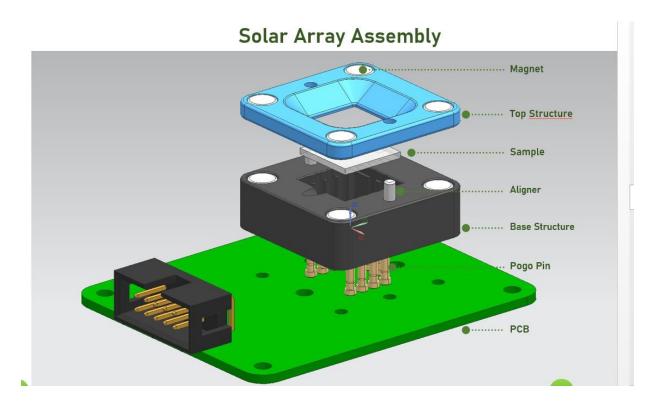


The Vision and Charter of PASF is to bring NanoTechnology to Life by offering Products, Solutions & Services from the Research Efforts at Centre for Nanosciences and Engineering —CeNSE IISc

Solutions and Services Offered

- I. Analog and Digitial Board Design- Altium.
- II. Firmware Development. –STM32/Arduino/Others
- III. Mechanical Housing Design and Modelling- Solid Works
- IV. 3D Printing –Bambu Carbon Fibre Printer.
- V. Prototype Development and Transfer to Mass Production-Customised Hardware/FW/SW Development.
- VI. Support TBI (Technology Business Incubation) & Startup's
- VII. Packaging of Microelectronics such as Wirebonding, Wafer Dicing, Laser Welding, Flip Chip Bonding.
- VIII. Design and Development of New Products based on Nanotechnology Research at CeNSE- IISc such as Gas Sensors, Pressure Sensors etc..
- IX. Provide Advanced Packaging Solutions with Focus on Research and Development- New (Ansys- SW).
- X. Semi Clean and Clean Room with ~2K Square Feet Area

Product Photos- Solar Array Silicon Assembly





Systems Engineering Products and Services

Gas Sensors & Transmitters



6 Channel Switch Multiplexer





- Senses Specific Gas Leakage such as H2, O2, NO2, N2H4.
- Provides 4-20ma.





- Monitors H2S- 0 to 500ppb
- Provides 20 Hour Battery Back up operation



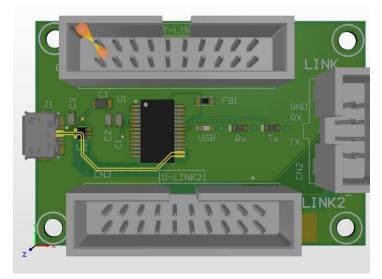
- 6 Channel Multiplexer 0 to 2V, 0 to 10ma.
- Characterise Silicon Wafer and interfaces to Lake View Probe Station.



Systems Engineering & Packaging Lab Products and Services

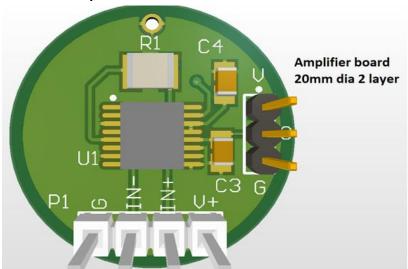


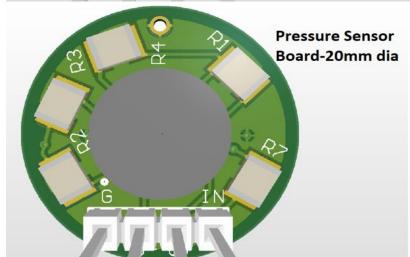
UART to USB Converter



- 5V, 3.3V UART Compatible Inputs
- USB 2.0 Specifications Compliant

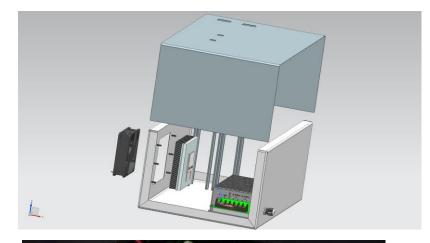
Pressure Sensor & Amplifier Boards





CeNSE-IISc Confidential Not to be disclosed w/o permission

Thermal Chamber Assembly



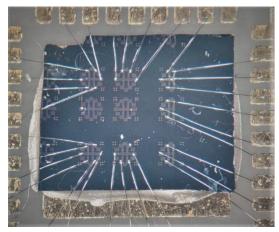




Systems Engineering & Packaging Lab Products and Services



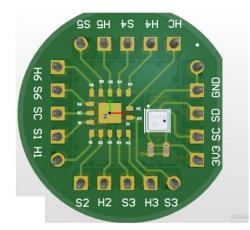
Windtunnel Velocity Measurement with 15 Die Packaged





Outer Package for **Velocity Measurement**

6 Element Die Mounting



- Monitors 6 Gases CO, CO2, NO2, O2, H2, **N2H4**
- 6 Individual Die

❖ Air Quality Monitor



- Monitors 6 Gases CO, CO2, NO2, SO2, RH, N2H4
- PM 2.5, PM10
- Real Time Data over Cloud





Systems Engineering & Packaging Lab Products and Services

MEMS PRESSURE TRANSDUCER







Activate Windows

Pressure Transducers of Various Types and Ranges

http://sysefandpackagingfacility.cense.iisc.ac.in/





PASF-TF 32 Design Services Tools

1. Hardware Design- Altium for Schematics, PCB Layout.

2. Firmware Development-STM32FXXX, Arduino Nano, Raspberry PI

3. Matlab Programming- Algorithm Development

4. Mech Design and 3d Modelling- Solid Works

For More Details Please Visit

http://sysefandpackagingfacility.cense.iisc.ac.in/ Pasf.cense@iisc.ac.in

